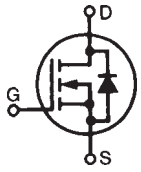
IXYS

High Voltage Power MOSFET

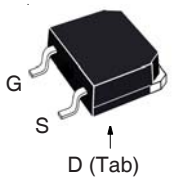
IXTT12N150HV

V_{DSS} = 1500V
I_{D25} = 12A
$R_{DS(on)}$ ≤ 2.2Ω

N-Channel Enhancement Mode
Fast Intrinsic Diode



TO-268HV



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	1500	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	1500	V
V_{GSS}	Continuous	±30	V
V_{GSM}	Transient	±40	V
I_{D25}	T_C = 25°C	12	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	40	A
I_A	T_C = 25°C	6	A
E_{AS}	T_C = 25°C	750	mJ
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	5	V/ns
P_D	T_C = 25°C	890	W
T_J		- 55 ... +150	°C
T_{JM}		150	°C
T_{stg}		- 55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
Weight		4	g

Features

- High Blocking Voltage
- High Voltage Package
- Fast Intrinsic Diode
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- High Voltage Power Supplies
- Capacitor Discharge
- Pulse Circuits

Symbol (T_J = 25°C, Unless Otherwise Specified)	Test Conditions	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 1mA	1500			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 250μA	2.5		4.5	V
I_{GSS}	V_{GS} = ±30V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			25	μA
	T_J = 125°C			500	μA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			2.2	Ω

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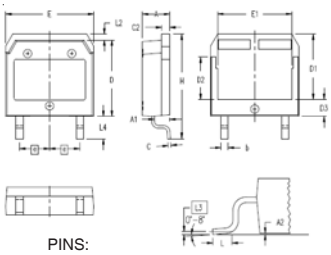
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 20V, I_D = 0.5 • I_{D25}, Note 1	8	13		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		3720		pF
C_{oss}			240		pF
C_{rss}			80		pF
$t_{d(on)}$	**Resistive Switching Times**		26		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		16		ns
$t_{d(off)}$	R_G = 2Ω (External)		53		ns
t_f			14		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		106		nC
Q_{gs}			17		nC
Q_{gd}			50		nC
R_{thJC}				0.14	°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			12	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			48	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.4	V
t_{rr}	I_F = 6A, -di/dt = 100A/µs		1.2		µs
I_{RM}	V_R = 100V, V_{GS} = 0V		24.5		A
Q_{RM}			14.8		µC

Note 1. Pulse test, t ≤ 300µs, duty cycle, d ≤ 2%.

TO-268HV Outline



PINS:
1 - Gate
2 - Source
3 - Drain

Dim.	Millimeter min	Millimeter max	Inches min	Inches max
A	4.90	5.10	0.193	0.201
A1	2.70	2.90	0.106	0.114
A2	0.02	0.25	0.001	0.100
b	1.15	1.45	0.045	0.057
C	0.40	0.65	0.016	0.026
C 2	1.45	1.60	0.057	0.063
D	13.80	14.00	0.543	0.551
D1	11.80	12.10	0.465	0.476
D2	7.50	7.80	0.295	0.307
D3	2.90	3.20	0.114	0.126
E	15.85	16.05	0.624	0.632
E1	13.30	13.60	0.524	0.535
e	5.45 BSC		0.215 BSC	
H	18.70	19.10	0.736	0.752
L	1.70	2.00	0.067	0.079
L2	1.00	1.15	0.039	0.045
L3	0.25 BSC		0.010 BSC	
L4	3.80	4.10	0.150	0.161

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or moreof the following U.S. patents: 4,835,592 4,860,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ T_J = 25ºC

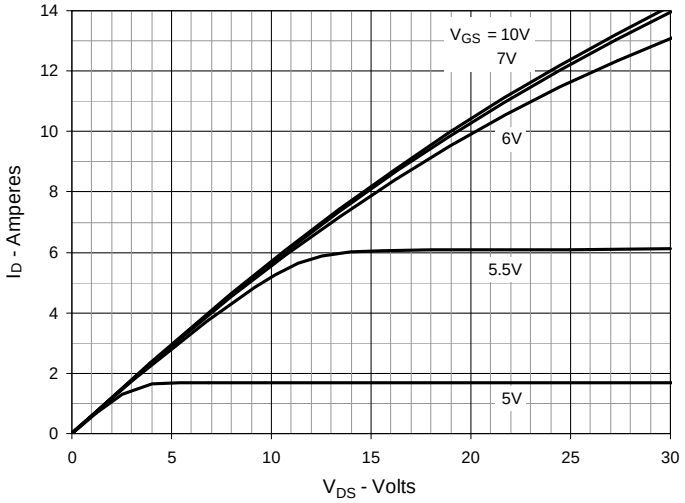


Fig. 2. Output Characteristics @ T_J = 125ºC

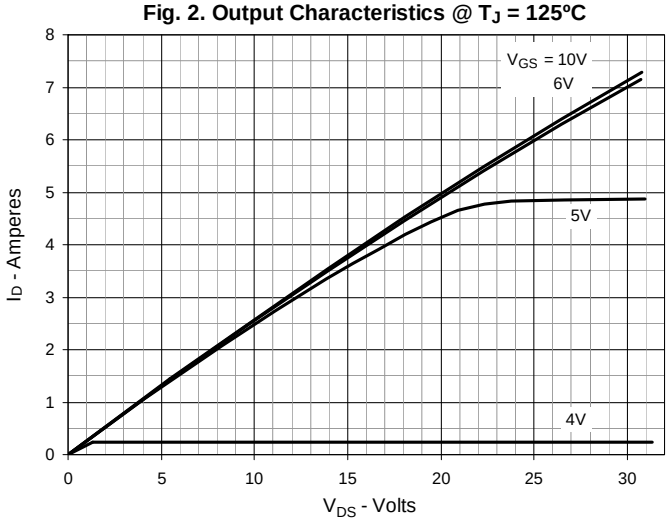


Fig. 3. $R_{DS(on)}$ Normalized to I_D = 6A Value vs. Junction Temperature

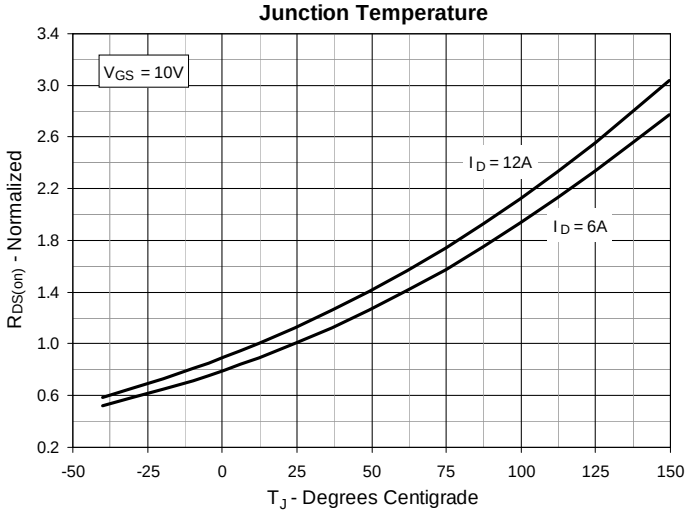


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 6A Value vs. Drain Current

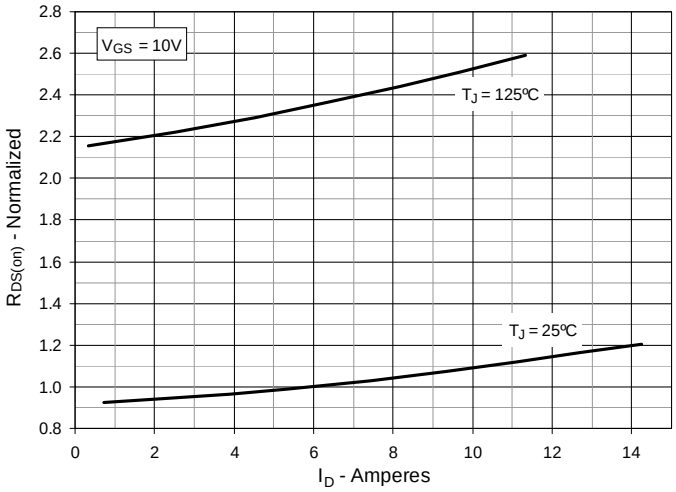


Fig. 5. Maximum Drain Current vs. Case Temperature

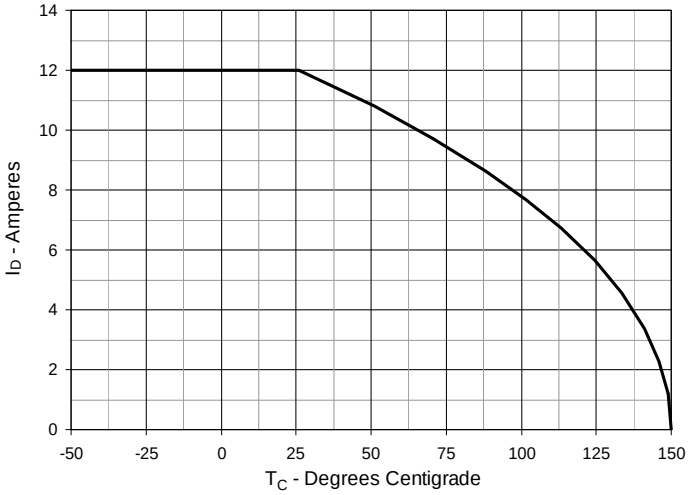
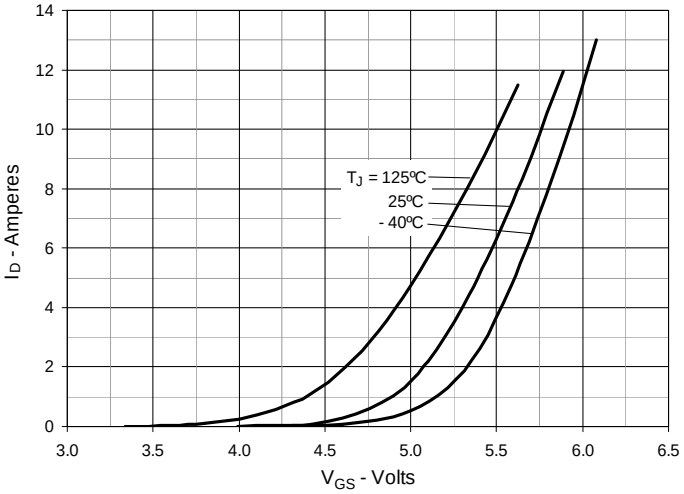


Fig. 6. Input Admittance



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Fig. 7. Transconductance

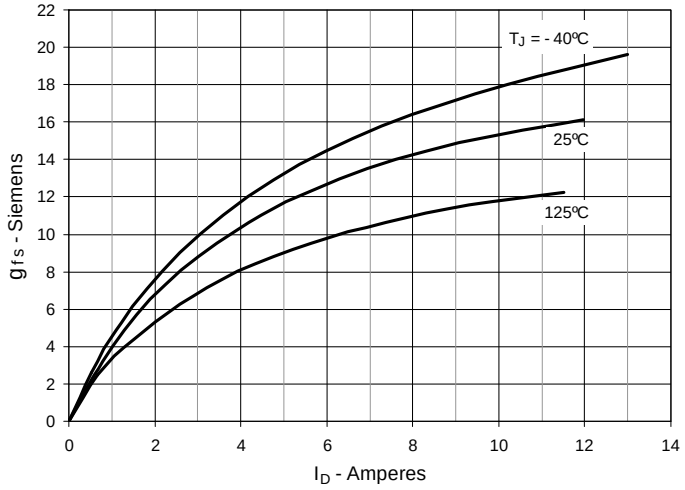


Fig. 8. Forward Voltage Drop of Intrinsic Diode

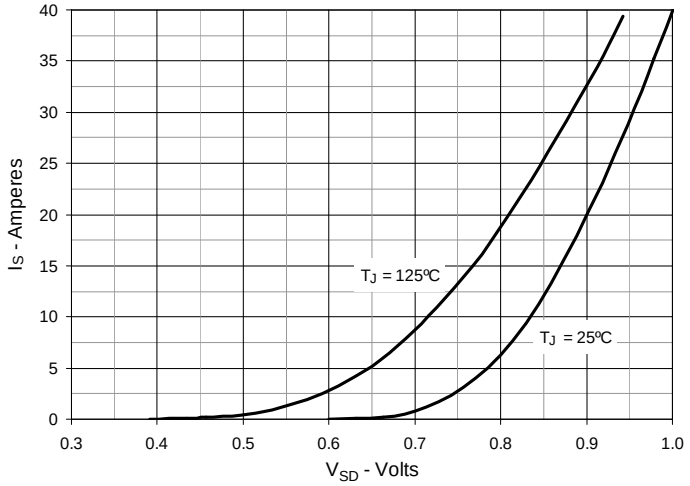


Fig. 9. Gate Charge

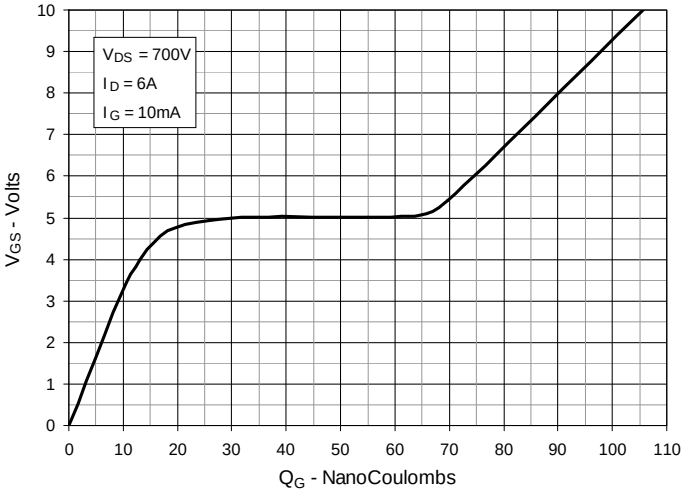


Fig. 10. Capacitance

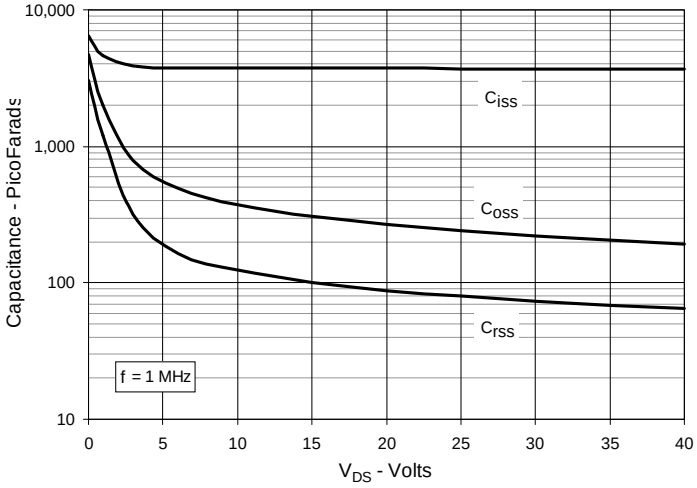


Fig. 11. Forward-Bias Safe Operating Area

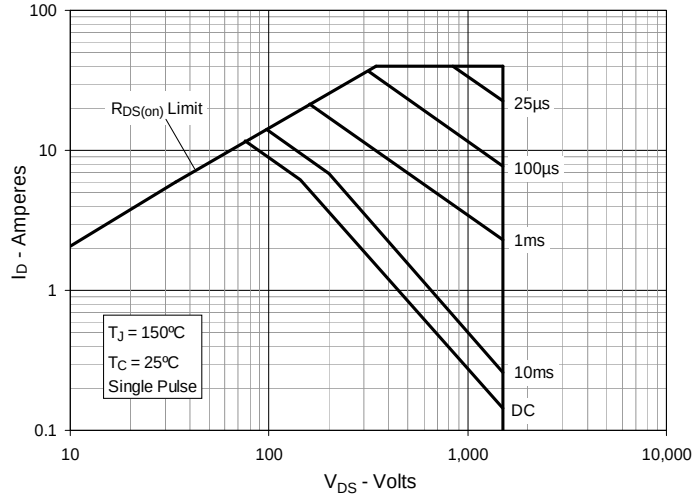
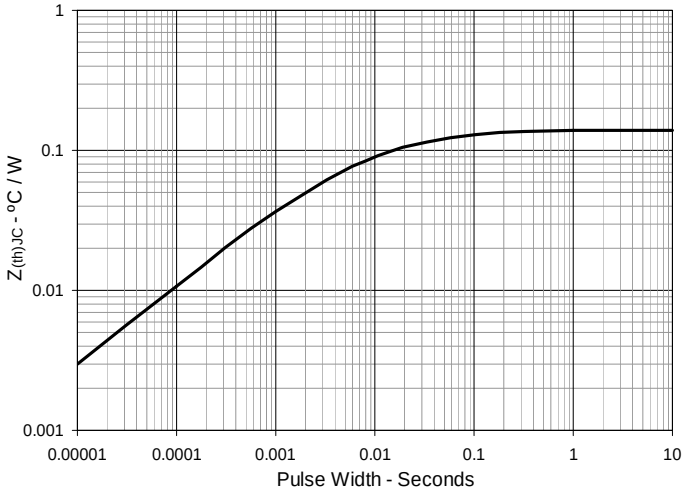


Fig. 12. Maximum Transient Thermal Impedance



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